2.5: Recommended Reflow Profile

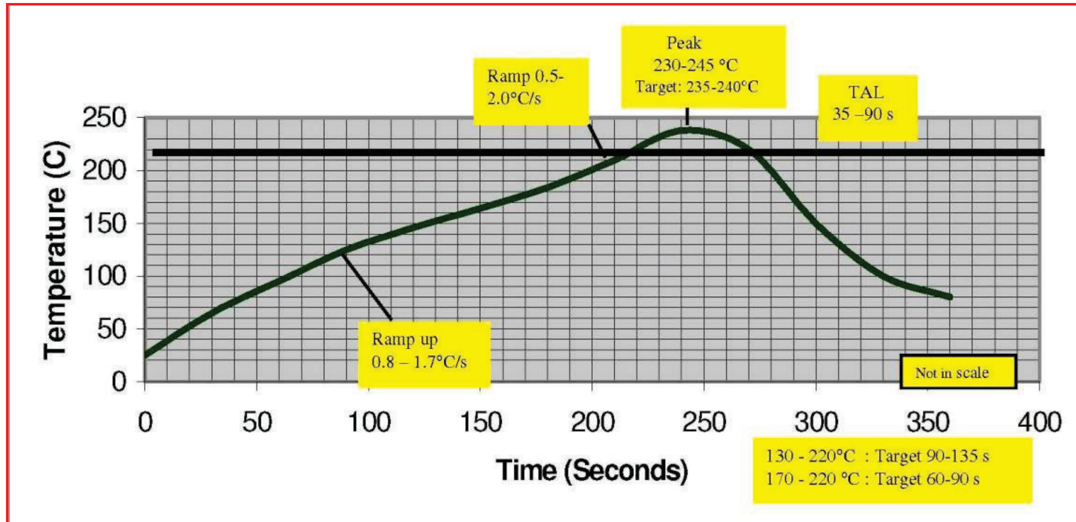

Figure 5: Reflow Profile

Note: The profile shown is based on SAC 305 solder (3% silver, 0.5% copper). We recommend the ALPHA OM-338 lead-free solder paste. This profile is provided mainly for guidance. The total dwell time depends on the thermal mass of the assembled board and the sensitivity of the components on it.

2.6: Baking Instructions

The RS9110-N-11-28 package is moisture sensitive and devices must be handled appropriately. After the devices are removed from their vacuum sealed packs, they should be taken through reflow for board assembly within 168 hours at room conditions, or stored at under 10% relative humidity. If these conditions are not met, the devices must be baked before reflow. The recommended baking time is nine hours at 125° C.